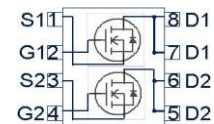
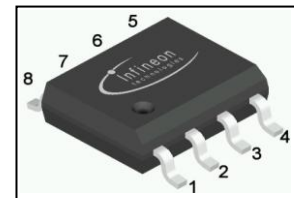


OptiMOS™ 2 Power-Transistor
Features

- For fast switching converters and sync. rectification
- Qualified according to JEDEC¹⁾ for target applications
- Super Logic level 2.5V rated; N-channel
- Dual n-channel
- Excellent gate charge x $R_{DS(on)}$ product (FOM)
- Low on-resistance $R_{DS(on)}$
- Avalanche rated
- Pb-free plating; RoHS compliant
- Halogen-free according to IEC61249-2-21

Product Summary

V_{DS}		20	V
$R_{DS(on),max}$	$V_{GS}=4.5\text{ V}$	30	mΩ
	$V_{GS}=2.5\text{ V}$	50	
I_D		6.5	A

PG-DSO-8


Type	Package	Marking
BSO330N02K	PG-DSO-8	330N2K

Maximum ratings, at $T_j=25\text{ °C}$, unless otherwise specified

Parameter	Symbol	Conditions	Value		Unit
			10 secs	steady state	
Continuous drain current	I_{D}	$V_{\text{gs}}=4.5\text{V}, T_{\text{C}}=25\text{ }^{\circ}\text{C}^{2)}$	6.5	5.4	A
		$V_{\text{gs}}=4.5\text{V}, T_{\text{C}}=70\text{ }^{\circ}\text{C}^{2)}$	5.2	4.3	
		$V_{\text{gs}}=2.5\text{V}, T_{\text{C}}=25\text{ }^{\circ}\text{C}^{2)}$	5.1	4.2	A
		$V_{\text{gs}}=2.5\text{V}, T_{\text{C}}=70\text{ }^{\circ}\text{C}^{2)}$	4	3.3	
Pulsed drain current	$I_{\text{D,pulse}}$	$T_{\text{C}}=25\text{ }^{\circ}\text{C}^{3)}$	26		
Avalanche energy, single pulse	E_{AS}	$I_{\text{D}}=6.5\text{ A}, R_{\text{GS}}=25\text{ }\Omega$	19		mJ
Reverse diode dv/dt	dv/dt	$I_{\text{D}}=6.5\text{ A}, V_{\text{DS}}=20\text{ V},$ $di/dt=200\text{ A}/\mu\text{s},$ $T_{\text{j,max}}=150\text{ }^{\circ}\text{C}$	6		kV/ μs
Gate source voltage	V_{GS}		± 12		V
Power dissipation	P_{tot}	$T_{\text{A}}=25\text{ }^{\circ}\text{C}^{2)}$	2.0	1.4	W
		$T_{\text{A}}=25\text{ }^{\circ}\text{C}^{1)}$	2.5		
Operating and storage temperature	$T_{\text{j}}, T_{\text{stg}}$		-55 ... 150		$^{\circ}\text{C}$
ESD Class			0 (0V to 250V)		
IEC climatic category; DIN IEC 68-1			55/150/56		

Thermal characteristics

Thermal resistance, junction - soldering point	R_{thJS}		-	-	50	K/W
Thermal resistance, junction - ambient	R_{thJA}	minimal footprint, $t_p \leq 10$ s	-	-	110	
		minimal footprint, steady state	-	-	150	
		6 cm ² cooling area ²⁾ , $t_p \leq 10$ s	-	-	63	
		6 cm ² cooling area ²⁾ , steady state	-	-	90	

Electrical characteristics, at $T_j = 25$ °C, unless otherwise specified

Static characteristics

Drain-source breakdown voltage	$V_{(BR)DSS}$	$V_{GS}=0$ V, $I_D=1$ mA	20	-	-	V
Gate threshold voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}$, $I_D=20$ μ A	0.7	0.95	1.2	
Zero gate voltage drain current	I_{DSS}	$V_{DS}=20$ V, $V_{GS}=0$ V, $T_j=25$ °C	-	-	1	μ A
		$V_{DS}=20$ V, $V_{GS}=0$ V, $T_j=125$ °C	-	-	100	
Gate-source leakage current	I_{GSS}	$V_{GS}=12$ V, $V_{DS}=0$ V	-	-	100	nA
Drain-source on-state resistance	$R_{DS(on)}$	$V_{GS}=2.5$ V, $I_D=5.1$ A	-	38	50	m Ω
		$V_{GS}=4.5$ V, $I_D=6.5$ A	-	24	30	
Gate resistance	R_G		-	1.3	-	Ω
Transconductance	g_{fs}	$ V_{DS} > 2 I_D R_{DS(on)max}$, $I_D=6.5$ A	10	20	-	S

¹⁾J-STD20 and JESD22

²⁾ Device on 40 mm x 40 mm x 1.5 mm epoxy PCB FR4 with 6 cm² (one layer, 70 μ m thick) copper area for drain connection. PCB is vertical in still air.

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	

Dynamic characteristics

Input capacitance	C_{iss}	$V_{GS}=0\text{ V}, V_{DS}=10\text{ V},$ $f=1\text{ MHz}$	-	550	730	pF
Output capacitance	C_{oss}		-	190	250	
Reverse transfer capacitance	C_{rss}		-	26	39	
Turn-on delay time	$t_{d(on)}$	$V_{DD}=10\text{ V}, V_{GS}=4.5\text{ V},$ $I_D=6.5\text{ A}, R_{G,ext}=1.6\text{ }\Omega$	-	7.4	-	ns
Rise time	t_r		-	16.8	-	
Turn-off delay time	$t_{d(off)}$		-	13.4	-	
Fall time	t_f		-	2.8	-	

Gate Charge Characteristics⁴⁾

Gate to source charge	Q_{gs}	$V_{DD}=10\text{ V}, I_D=6.5\text{ A},$ $V_{GS}=0\text{ to }4.5\text{ V}$	-	1.2	1.6	nC
Gate charge at threshold	$Q_{g(th)}$		-	0.5	0.7	
Gate to drain charge	Q_{gd}		-	0.7	1.1	
Switching charge	Q_{sw}		-	1.4	2	
Gate charge total	Q_g		-	3.7	4.9	
Gate plateau voltage	$V_{plateau}$		-	2.2	-	V
Gate charge total, sync. FET	$Q_{g(sync)}$	$V_{DS}=0.1\text{ V},$ $V_{GS}=0\text{ to }4.5\text{ V}$	-	3.4	4.5	nC
Output charge	Q_{oss}	$V_{DD}=10\text{ V}, V_{GS}=0\text{ V}$	-	2.6	3.4	

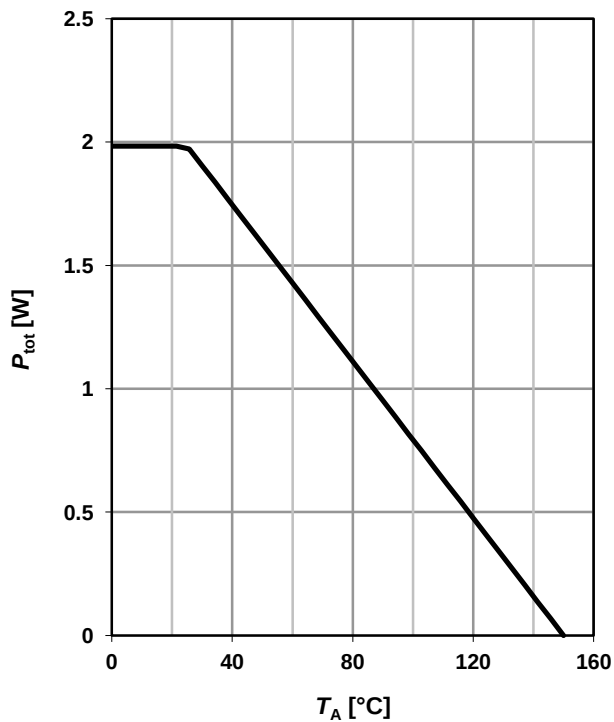
Reverse Diode

Diode continuous forward current	I_S	$T_C=25\text{ }^\circ\text{C}$	-	-	1.5	A
Diode pulse current	$I_{S,pulse}$		-	-	26	
Diode forward voltage	V_{SD}	$V_{GS}=0\text{ V}, I_F=6.5\text{ A},$ $T_J=25\text{ }^\circ\text{C}$	-	0.88	1.2	V
Reverse recovery time	t_{rr}	$V_R=10\text{ V}, I_F=6.5\text{ A},$ $di_F/dt=100\text{ A}/\mu\text{s}$	-	14	-	ns
Reverse recovery charge	Q_{rr}	$V_R=10\text{ V}, I_F=6.5\text{ A},$ $di_F/dt=100\text{ A}/\mu\text{s}$	-	4.8	-	nC

⁴⁾ See figure 16 for gate charge parameter definition

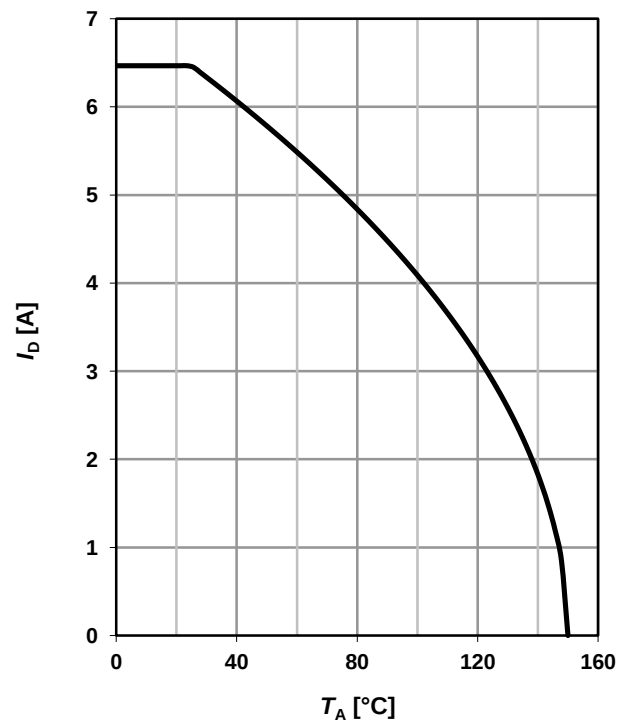
1 Power dissipation

$$P_{\text{tot}} = f(T_A); t_p \leq 10 \text{ s}$$



2 Drain current

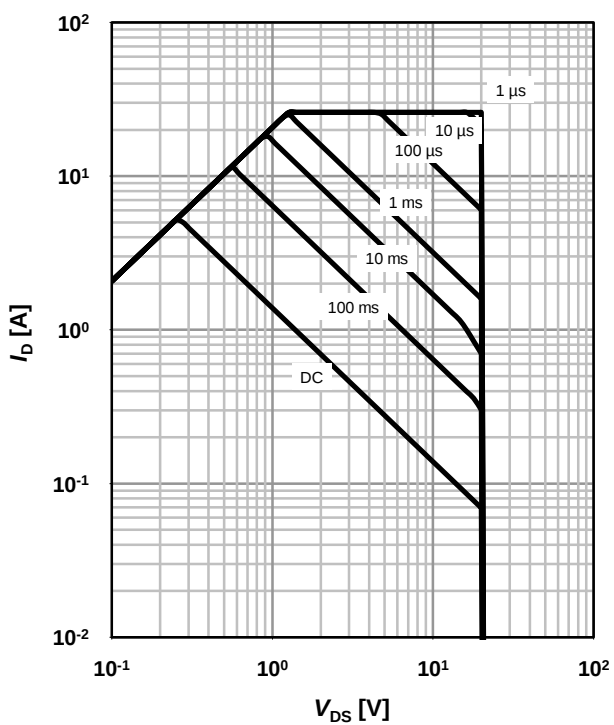
$$I_D = f(T_A); V_{GS} \geq 4.5 \text{ V}; t_p \leq 10 \text{ s}$$



3 Safe operating area

$$I_D = f(V_{DS}); T_A = 25^\circ\text{C}^{(1)}; D = 0$$

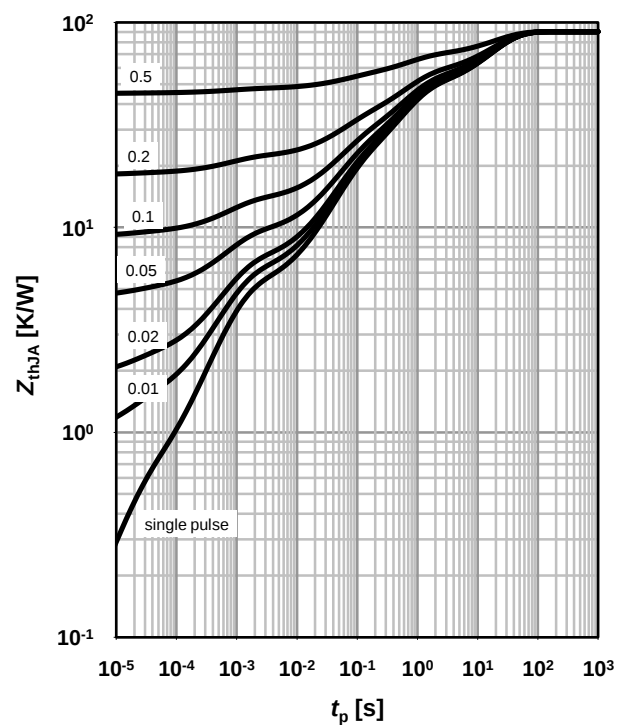
parameter: t_p



4 Max. transient thermal impedance

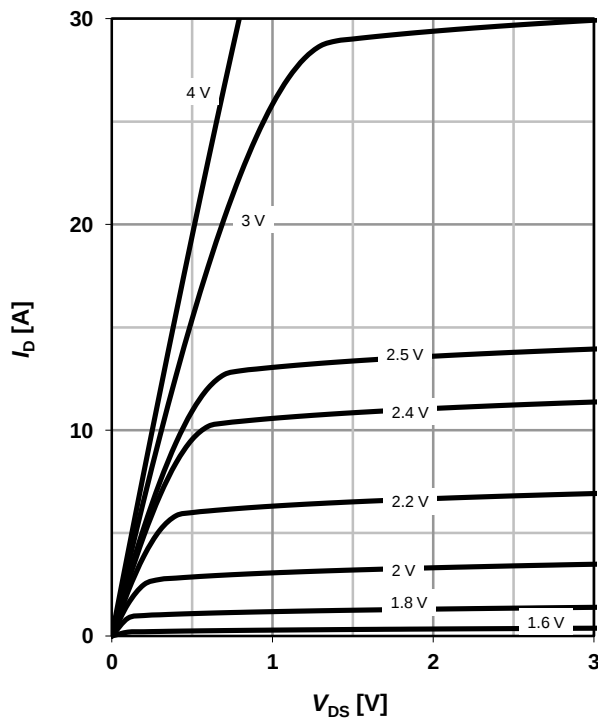
$$Z_{\text{thJA}} = f(t_p)^{(2)}$$

parameter: $D = t_p/T$



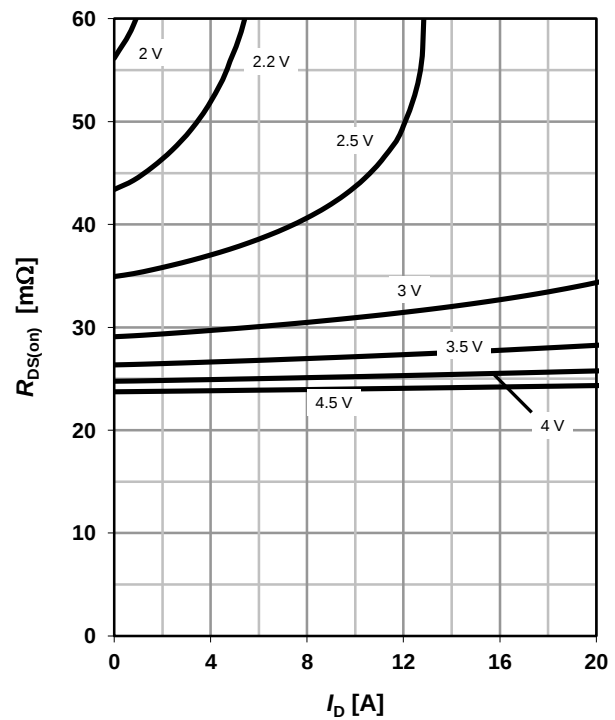
5 Typ. output characteristics

 $I_D = f(V_{DS}); T_j = 25^\circ\text{C}$

parameter: V_{GS}


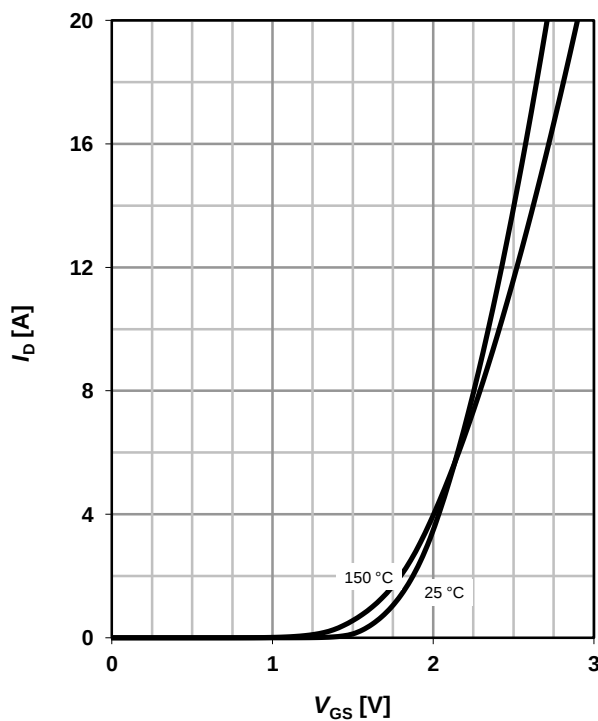
6 Typ. drain-source on resistance

 $R_{DS(on)} = f(I_D); T_j = 25^\circ\text{C}$

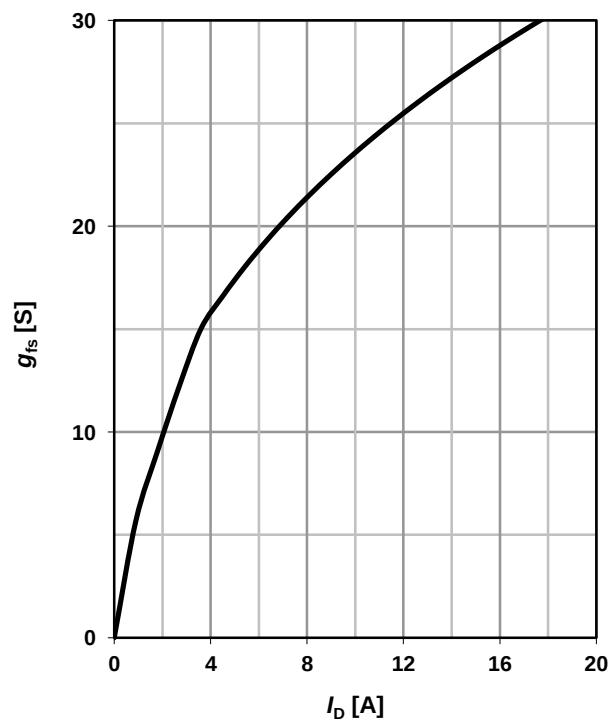
parameter: V_{GS}


7 Typ. transfer characteristics

 $I_D = f(V_{GS}); |V_{DS}| > 2|I_D|R_{DS(on)max}$

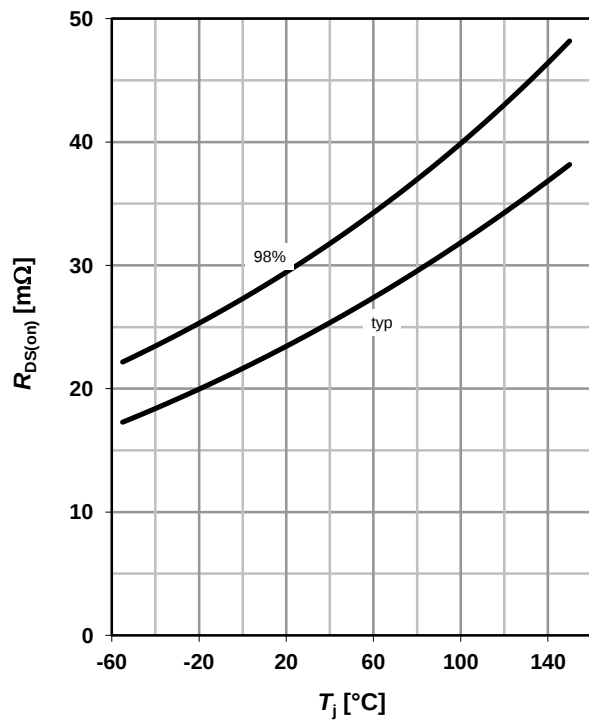
parameter: T_j


8 Typ. forward transconductance

 $g_{fs} = f(I_D); T_j = 25^\circ\text{C}$


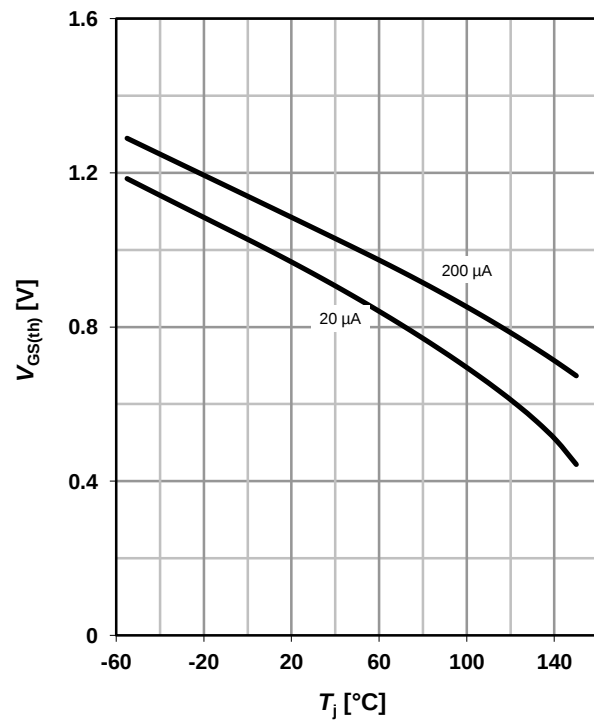
9 Drain-source on-state resistance

$$R_{DS(on)} = f(T_j); I_D = 6.5 \text{ A}; V_{GS} = 4.5 \text{ V}$$



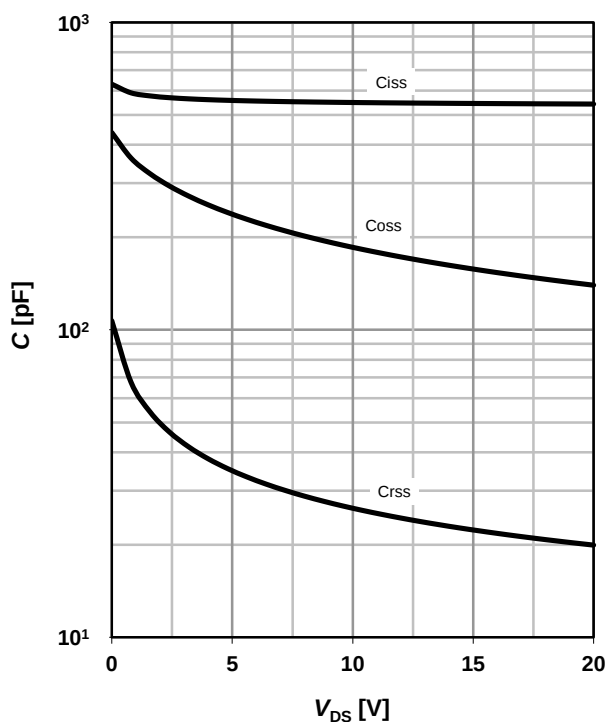
10 Typ. gate threshold voltage

$$V_{GS(th)} = f(T_j); V_{GS} = V_{DS}$$



11 Typ. capacitances

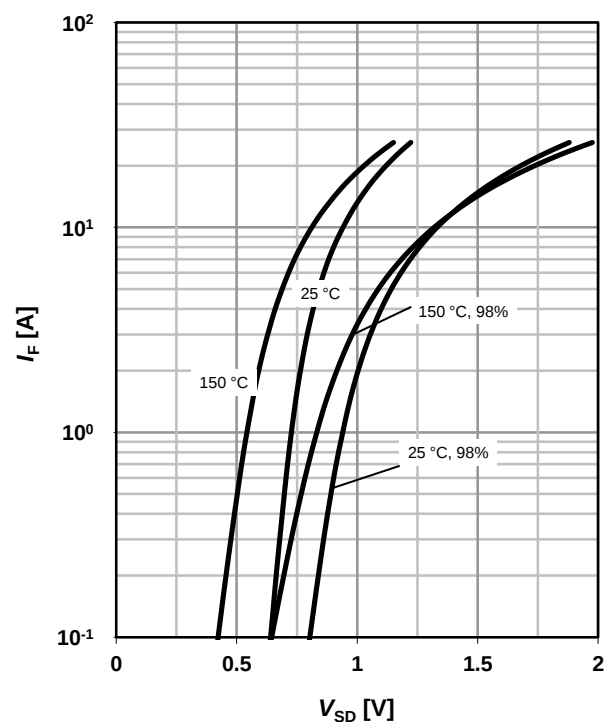
$$C = f(V_{DS}); V_{GS} = 0 \text{ V}; f = 1 \text{ MHz}$$



12 Forward characteristics of reverse diode

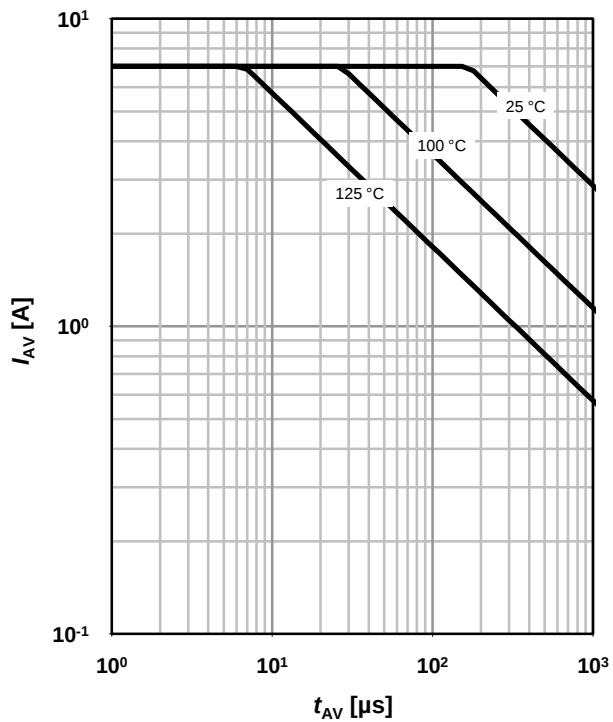
$$I_F = f(V_{SD})$$

parameter: T_j



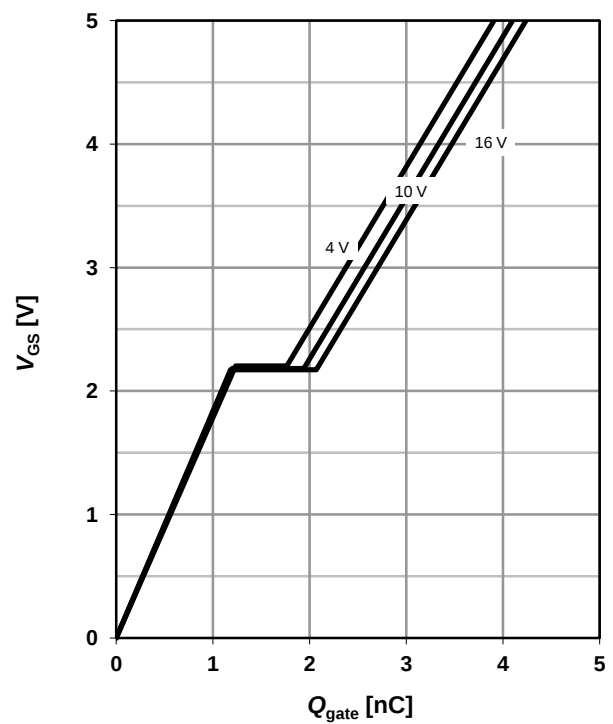
13 Avalanche characteristics

 $I_{AS}=f(t_{AV}); R_{GS}=25\ \Omega$

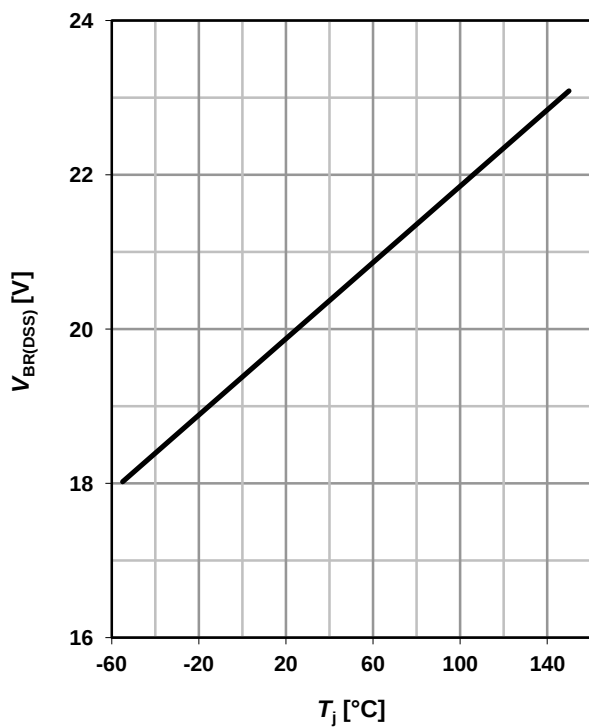
parameter: $T_{j(\text{start})}$


14 Typ. gate charge

 $V_{GS}=f(Q_{\text{gate}}); I_D=6.5\ \text{A pulsed}$

parameter: V_{DD}


15 Drain-source breakdown voltage

 $V_{BR(DSS)}=f(T_j); I_D=1\ \text{mA}$


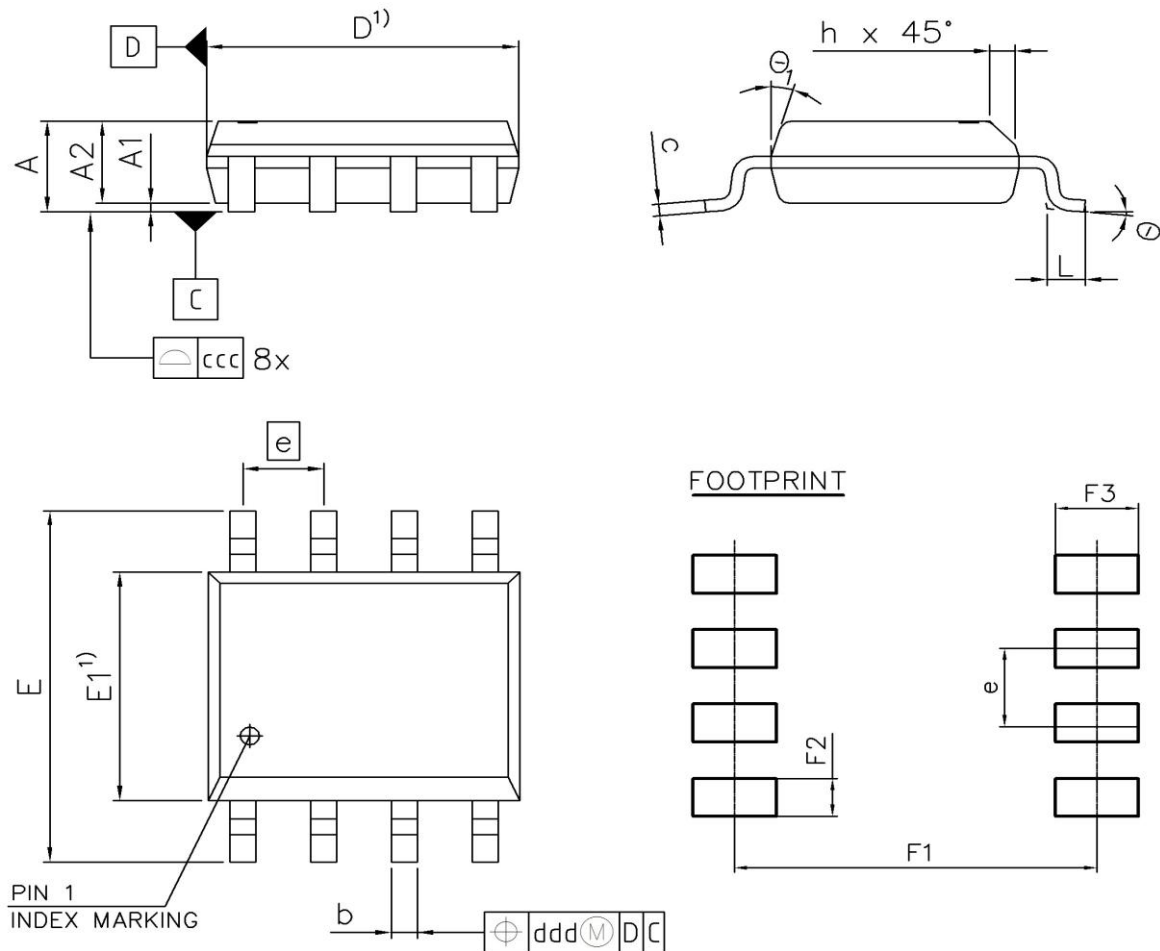
16 Gate charge waveforms



Package Outline

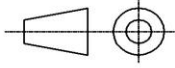
PG-TDSON-8

PG-DSO-8: Outline



1) DOES NOT INCLUDE MOLD FLASH OR PROTRUSIONS.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	-	1.75	-	0.069
A1	0.10	-	0.004	-
A2	1.25	1.65	0.049	0.065
b	0.35	0.51	0.014	0.020
c	0.17	0.25	0.007	0.010
D	4.80	5.00	0.189	0.197
E	5.80	6.20	0.228	0.244
E1	3.80	4.00	0.150	0.157
e	1.27		0.050	
N	8		8	
L	0.39	0.89	0.015	0.035
h	0.23	0.50	0.009	0.020
Θ	0°	8°	0°	8°
Θ_1	-	19°	-	19°
ccc	0.10		0.004	
ddd	0.25		0.010	
F1	5.59	5.79	0.220	0.228
F2	0.55	0.75	0.022	0.030
F3	1.21	1.41	0.048	0.056

DOCUMENT NO. Z8B00003333
SCALE 0 1.0 2mm
EUROPEAN PROJECTION 
ISSUE DATE 09.01.2008
REVISION 02

Published by
Infineon Technologies AG
81726 Munich, Germany
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